REMARKS

Entry of the amendments to the claims before examination of the application is respectfully requested.

If there are any questions regarding this Preliminary Amendment or this application in general, a telephone call to the undersigned would be appreciated since this should expedite the prosecution of the application for all concerned.

It is respectfully requested that, if necessary to effect a timely response, this paper be considered as a Petition for an Extension of Time sufficient to effect a timely response and shortages in other fees, be charged, or any overpayment in fees be credited, to the Account of Evenson, McKeown, Edwards & Lenahan, P.L.L.C., Deposit Account No. 05-1323 (Docket #381NP/50670).

Respectfully submitted,

November 21, 2001

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

Please amend claims 12-13 and 15-16 as follows:

12. (Amended) An electrolytic gold plating apparatus according to [any one of claims 9 to 11] Claim 9 or 10, wherein said means for measuring said sulfurous acid in said complex or sulfuric acid is an automatic titrator or a liquid chromatograph.

13. (Amended) An electrolytic gold plating apparatus according to [any one of claims 9 to 12] Claim 9 or 10, which comprises a monitoring unit for displaying a value measured by at least one of said means for measuring a light intensity, said means for measuring said pH, said means for measuring sulfurous acid and said means for measuring sulfuric acid.

15. (Amended) An electrolytic gold plating apparatus according to [any one of claims 8 to 14] Claims 8 to 10 and 14, which comprises:

an automatic adding solution supply unit for adding said plating solution based on a value obtained by measuring at least one of an amount of gold colloid of said plating solution, a value of pH of said plating solution, a concentration of sulfurous acid in gold sulfite complex of said plating solution and a concentration of sulfuric acid of said plating solution;

an automatic pH adjustment unit for adjusting pH; and

an automatic water supply unit for supplying water for evaporated water.

16. (Amended) An electrolytic gold plating apparatus according to [any one of claims 8 to 15] Claims 8 to 10 and 14, which comprises:

an anode, an object to be plated and an opening portion in a plating bath, said anode being vertically arranged, said object to be plated being arranged opposite to said anode, said opening portion being arranged at a side surface portion of said plating bath;

a substrate stage for vacuum-holding said object to be plated, said substrate stage detachably attached to said plating bath in a state of blocking said opening portion; and

a pushing unit for pushing and releasing said substrate stage to and from said opening portion.